

Title (en)  
A THIN FILM RESISTOR DEVICE AND A METHOD OF MANUFACTURE THEREFOR

Title (de)  
DÜNNSCHICHTWIDERSTAND UND DESSEN HERSTELLUNGSVERFAHREN

Title (fr)  
RESISTANCE EN COUCHE MINCE ET PROCEDE DE FABRICATION

Publication  
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Application  
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Abstract (en)  
[origin: WO0106547A1] The present invention provides a thin film resistor and method of manufacture therefor. The thin film resistor comprises a resistive layer located on a first dielectric layer, first and second contact pads located on the resistive layer, and a second dielectric layer located over the resistive layer and the first and second contact pads. In an illustrative embodiment, the thin film resistor further includes a first interconnect that contacts the first contact pad and a second interconnect that contacts the second contact pad.

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